

# Conductive adhesive - Filler, Low melting point metal

Low temperature thermosetting, Stable at higher temperature after hardening

## 1. Low temp bonding

- ▶ Low melting point: less 150 degC
- ▶ Low thermosetting temp

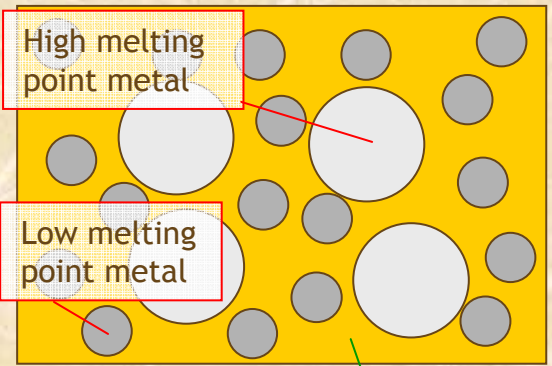
## 2. Stable at high temp

- ▶ Once the hardening completes, does not melt at the temp less than 250 degC

## 3. No need for Clean

- ▶ Adhesive has the feature of the flux

Before bonding  
: Conductive adhesive



adhesive  
:Epoxy adhesive having the feature of the flux

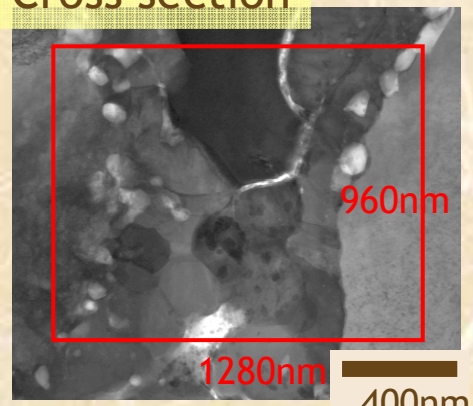


After bonding

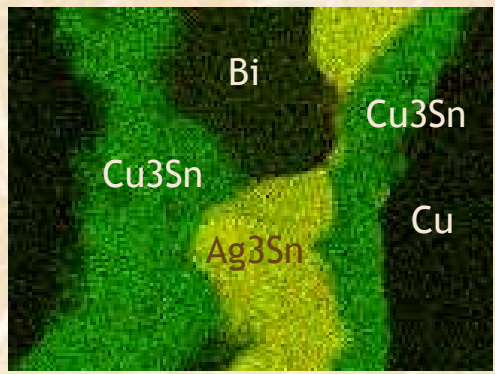
## Stable at high temperature

High melting point alloy due to the reaction of Sn with Ag, Cu etc.

## Cross section



TEM



STEM-EDX

**Technology established as appropriate for the PWB mount**